MAXIMUM SOLUTIONS

Mill-Max Through-hole Receptacles on Tape for Automated Assembly



For customers utilizing an intrusive reflow soldering* process, purchasing Mill-Max socket receptacles supplied on tape and reel offer significant time savings by eliminating manual component placement onto the PCB.

These receptacles (discrete sockets) come on carrier tape per EIA-481 to feed automated 'pick & place' assembly equipment. Our standard reel size is 13".

Mill-Max offers RoHS compliant plating options. Instead of traditional tin/lead plating on the receptacle's shell and contact, a pure matte tin with oxide and whisker inhibitors can be specified.

For more information, visit: www.mill-max.com/PR558.

*Intrusive reflow (also called "pin-in-paste") is a technique of using conventional through-hole components in a reflow soldering process. The receptacles are placed into plated-through-holes in the circuit board (solder paste has previously been screen printed on pads adjacent to the holes) and the board is reflowed in the same pass as other SMT components. Solder will fill the plated-through-holes and achieve solder joints as reliable as wave soldering. The OFP® barrier prevents solder paste from being picked-up inside the contact during pick 'n place assembly. "Overprinting" paste on the solder mask can be used to adjust the volume of paste required to fill each hole.



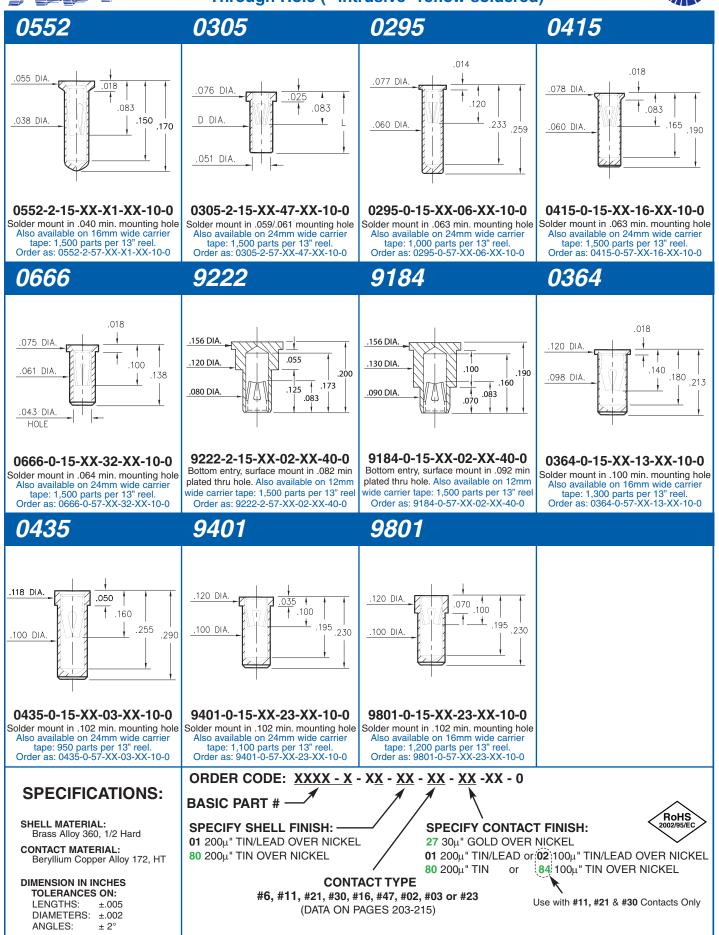
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RECEPTACLES ON TAPE per EIA-481 for automated "pick & place" assembly. Through Hole ("intrusive" reflow soldered)



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